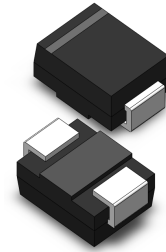


**VOLTAGE RANGE: 400V**  
**CURRENT: 1.0 A**

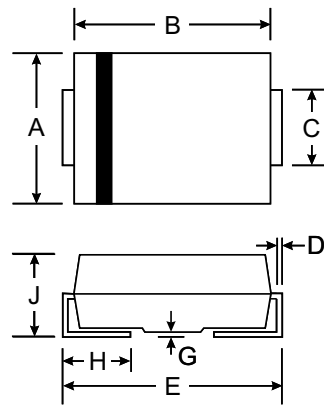


### Features

- Miniature Size, Surface Mount Device
- Low Forward Voltage Drop
- High Surge Capability
- Low Power Loss, High Efficiency
- Ultra-Fast Recovery
- Packaged in 12mm Tape and Reel
- Not Rolling During Assembly

### Mechanical Data

- Case: SMB/DO-214AA, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)



SMB(DO-214AA)		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.70
C	1.91	2.21
D	0.15	0.31
E	5.00	5.59
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

### Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	EC11FS4	Unit
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	400	V
Non-repetitive Peak Reverse Voltage	V <sub>RSM</sub>	440	V
Average Rectified Forward Current 50Hz Half Sine Wave Resistive Load	I <sub>O</sub>	0.76 1.0	A
R.M.S. Forward Current	I <sub>F(RMS)</sub>	1.57	A
Surge Forward Current 50Hz Half Sine Wave, 1 cycle, Non-repetitive	I <sub>FSM</sub>	20	A
Operating Junction Temperature Range	T <sub>jw</sub>	-40 to +150	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

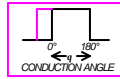
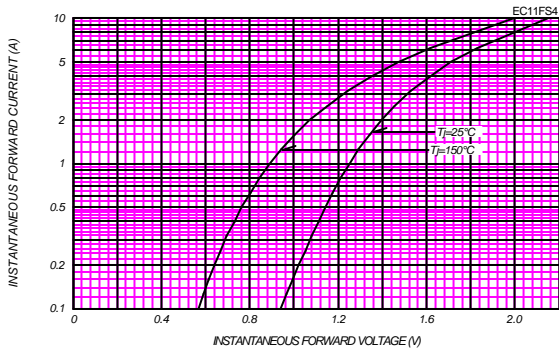
Characteristic	Symbol	Min.	Typ.	Max.	Unit
Peak Reverse Current T <sub>j</sub> = 25 °C, V <sub>RM</sub> = V <sub>RRM</sub>	I <sub>RM</sub>	-	-	20	μA
Peak Forward Voltage T <sub>j</sub> = 25 °C, I <sub>FM</sub> = 0.8A	V <sub>FM</sub>	-	-	1.25	V
Reverse Recovery Time I <sub>FM</sub> = 1A, -di/dt = 50A/μs, T <sub>a</sub> = 25 °C	t <sub>rr</sub>	-	-	30	ns
Thermal Resistance Junction to Ambient	R <sub>th(j-a)</sub>	*1	-	157	°C /W
		*2	-	108	

1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

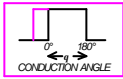
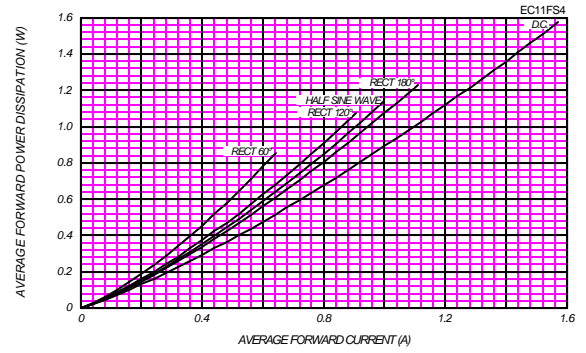
2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)



FORWARD CURRENT VS. VOLTAGE

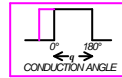
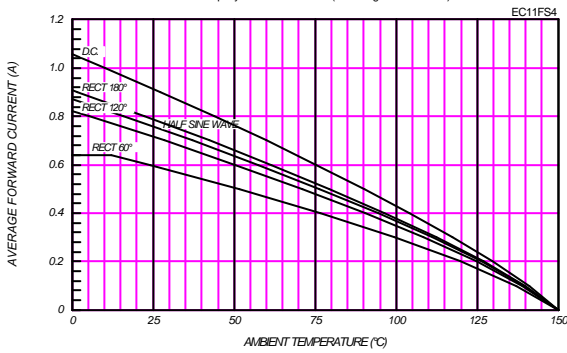


AVERAGE FORWARD POWER DISSIPATION



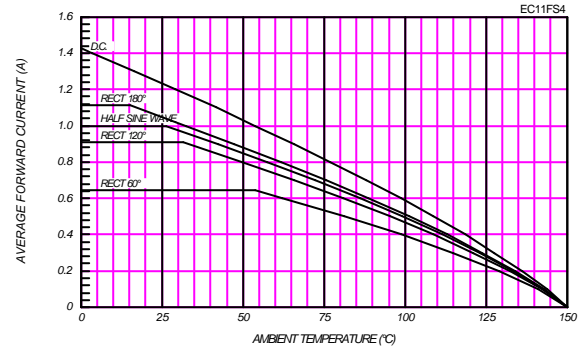
AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Glass-Epoxy Substrate Mounted(Soldering Land=2x2mm)



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Alumina Substrate Mounted(Soldering Land=2x2mm)



SURGE CURRENT RATINGS

f=50Hz; Half Sine Wave, Non-Repetitive, No Load

